

SISPAD 2004



International Conference on Simulation of Semiconductor Processes and Devices

September 2-4, 2004, Munich, Germany



Second Call for Papers

Scope

The conference provides an opportunity for the presentation of recent advances in modeling and simulation of semiconductor devices, processes and equipment for manufacturing.

Topics may include:

- Device simulation including quantum effects and nanodevices in silicon and compound semiconductors
- Process modeling and simulation including both continuum and atomistic approaches
- Equipment, topography and lithography simulation
- Circuit modeling including interconnects
- Integration of process, device and circuit simulation
- High performance computing and advanced numerical methods
- Compact modeling and integration of device/circuit simulation
- Simulation of mechatronical micro- and nanodevices
- Calibration of models and verification and benchmarking of simulators

Abstracts

Authors should submit 30 copies of a two-page abstract including figures. The abstract should include: title, 1st author's name and complete mailing address, names of additional authors and e-mail addresses. Authors will be notified by April 30, 2004. A camera-ready copy of a four-page extended abstract will be required from the authors of the accepted papers by June 1, 2004 for inclusion in the 2004 SISPAD Proceedings.

Deadline for submission of abstracts: February 28, 2004

The abstract should be sent to: Gerhard Wachutka Institute for Physics of Electrotechnology Munich University of Technology Arcisstrasse 21, 80290 Munich, Germany E-mail: sispad04@tep.ei.tum.de Tel.: +49-89-289 23122, Fax: +49-89-289 23164

Selection Criteria

The degree to which the two-page abstract deals with the following criteria will strongly affect whether the paper is selected:

- 1) What is the motivation for your paper?
- 2) What is new or original and how does it differ from previous work?
- 3) What is its impact or significance?
- 4) What are the major and specific results?

Organization

Gerhard Wachutka, Conference Chair Gabriele Schrag, Program Organization Munich University of Technology, Germany

Conference Venue

The conference will be held at the FORUM Hotel, located close to the historic center of Munich. In addition to the conference technical program, several social activities are being planned to allow attendees ample opportunity to enjoy their staying.

Updated information for the conference can be found at: http://www.tep.ei.tum.de/sispad04